

Descriptions

The RLCS23159 is a dual SPDT low on-resistance analog switch. It can operate from a single 1.5V to 5.5V power supply. The device offers low ON-state resistance and excellent ON-state resistance matching with break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device is capable of true isolation. Even when COMx overrides VCC, very little current will flow back to the supply.

Features

- QFN-2x1.5-10L and MSOP-10 Package
- Low On-resistance, $R_{on}=1.5\Omega$ when $COM_x=5V$
- 1.8V Logic Compatible Control Pin
- COMx Overrides VCC to Achieve True Isolation Even When Supply Is Dead
- High Off-Isolation: **-100dB @ 100KHz**
- Low Channel-to-Channel Crosstalk: **-97dB @ 100KHz**
- High Bandwidth (**-3dB @700MHz**) Suitable For USB2.0 High-Speed Routing
- Low Quiescent Current (<2uA) With Very Wide Supply Range (1.5V ~ 5.5V)

Applications

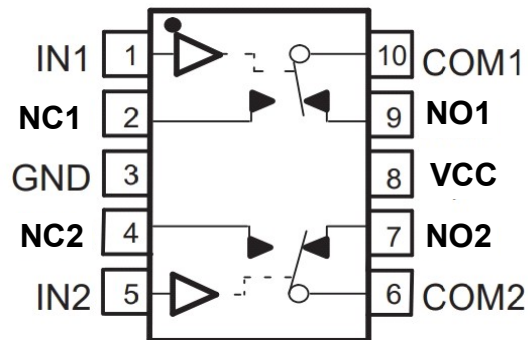
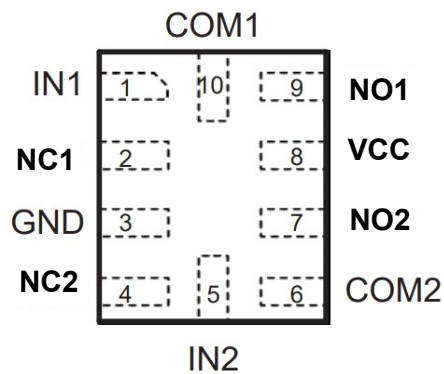
- Audio
- Video
- UART, USB2.0 Signal and Supply Routing
- Cell phones
- TWS headset
- USB Type-C Mic/Gnd Switch
- DC Motor Drive

Order Information

Package		Part Number	Quantity Per Reel
QFN 2.0 x 1.5 -10L	Tape and Reel	RLCS23159QN10/R6	3,000PCS
MSOP -10L	Tape and Reel	RLCS23159MP10/R6	3,000PCS

Functions and Pin Configuration

Pin Number	Symbol	Descriptions
1, 5	IN _x	Logic Input Control
2, 4	NC _x	Analog/Digital Signal Ports (Normally closed)
3	GND	Ground
6, 10	COM _x	Common Signal Ports
7, 9	NO _x	Analog/Digital Signal Ports (Normally open)
8	VCC	Single Power Supply

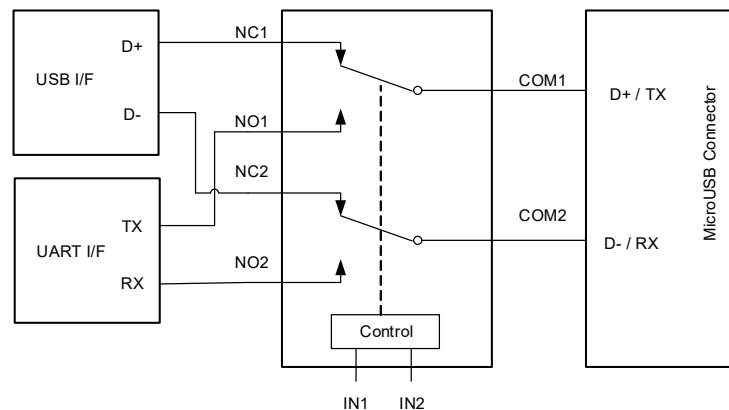
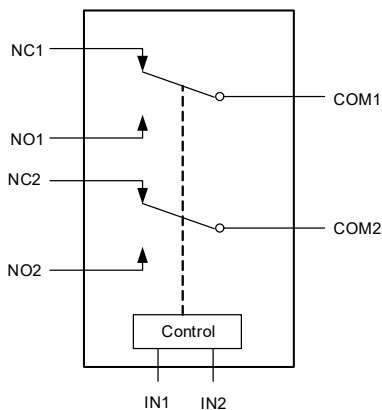


Pin configuration (Top view)

Function Descriptions

Logic Input(IN _x)	Function
0	NC1=COM1 and NC2=COM2
1	NO1=COM1 and NO2=COM2

Note: X= 1 or 2



Absolute Maximum Ratings ⁽¹⁾

Parameter	Symbol	Value	Unit
Supply Voltage	V _{CC}	-0.3 ~ 6.5	V
Control Input Voltage	V _{IN}	-0.3 ~ 6.5	V
Continuous Current Through NO, NC, COM		±100	mA
Peak Current Through NO, NC, COM (pulsed at 1ms 50% duty cycle)		±200	mA
Storage Temperature Range	T _{STG}	-55 ~ 150	°C
Junction Temperature under Bias	T _J	150	°C
Lead Temperature (Soldering, 10 seconds)	T _L	260	°C
Power Dissipation	P _D	250	mW

Recommend operating ratings ⁽²⁾

Parameter	Symbol	Value	Unit
Supply Voltage Operating	V _{CC}	1.5 ~ 5.5	V
Control Input Voltage	V _{IN}	-0.3 ~ 5.5	V
Input Signal Voltage	V _{COM}	-0.3 ~ 5.5	V
Operating Temperature	T _A	-40 ~ 85	°C
Thermal Resistance	R _{θJA}	360	°C/W

Note:

1. “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied.

DC Electronics Characteristics (Ta=25°C, VCC=3.3V, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input logic high level	V_{IH}	VCC: 3.3 ~ 5.5V	1.6			V
		VCC: 1.5 ~ 3.3V	1.4			V
Input logic low level	V_{IL}	VCC: 3.3 ~ 5.5V			0.6	V
		VCC: 1.5 ~ 3.3V			0.4	V
Supply quiescent current	I_{CC}	$I_{COM}=0$, $V_{IN}=0$ or $V_{IN}=VCC$			1.0	uA
Increase in I_{CC} per input	I_{CCT}	$I_{COM}=0$, VCC=4.5V $V_{IN}>1.8$ or $V_{IN}<0.5$			1.0	uA
Off state leakage from COM _x to NC _x (or NO _x)	I_{COMx}	$V_{COM}=5.5V$, $V_{NC(or NO)}=0V$			±2.0	uA
On-Resistance	R_{ON1}	$V_{COM}=0 \sim 0.5V$, $I_{COM}=30mA$		3.0	3.5	Ω
	R_{ON2}	$V_{COM}=0.5 \sim 2.0V$, $I_{COM}=30mA$		3.6	3.9	Ω
	R_{ON3}	$V_{COM}=2.0 \sim 4.0V$, $I_{COM}=30mA$		2.5	3.5	Ω
	R_{ON4}	$V_{COM}=4.0 \sim 5.5V$, $I_{COM}=30mA$		1.5	1.8	Ω
On-Resistance Flatness	R_{FLAT1}	$V_{COM}=0 \sim 0.5V$, $I_{COM}=30mA$		0.7		Ω
	R_{FLAT2}	$V_{COM}=0.5 \sim 2.0V$, $I_{COM}=30mA$		0.5		Ω
	R_{FLAT3}	$V_{COM}=2.0 \sim 4.0V$, $I_{COM}=30mA$		1.6		Ω
	R_{FLAT4}	$V_{COM}=4.0 \sim 5.5V$, $I_{COM}=30mA$		0.3		Ω
On-Resistance Matching Between Channels	ΔR_{ON}	$V_{COM}=0 \sim 5.5V$, $I_{COM}=30mA$,		0.1	0.2	Ω

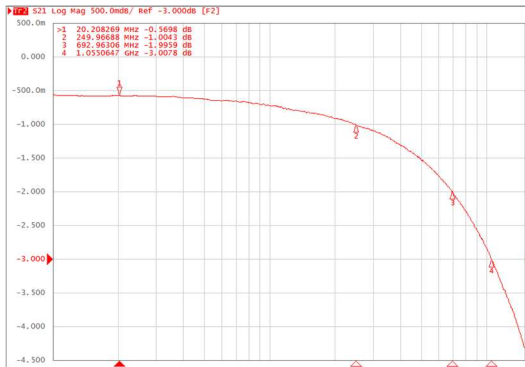
AC Electronics Characteristics (Ta=25°C, VCC=3.3V, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Turn-On Time	T_{ON}	$V_{COM}=1.5V$, $C_L=35pF$, $R_L=50\Omega$		200		ns
Turn-Off Time	T_{OFF}	$V_{COM}=1.5V$, $C_L=35pF$, $R_L=50\Omega$		200		ns
Break-Before-Make time	T_{BBM}	$V_{COM}=1.5V$, $C_L=35pF$, $R_L=50\Omega$		500		ns
-3dB Bandwidth	BW	$R_L=50\Omega$, $C_L=0pF$		850		MHz
Off isolation	OIRR	F=1KHz, $R_L=50\Omega$		-81		dB
		F=10KHz, $R_L=50\Omega$		-80		dB
Crosstalk	Xtalk	F=1KHz, $R_L=50\Omega$		-83		dB
		F=10KHz, $R_L=50\Omega$		-82		dB
Total Harmonic Distortion	THD	F=20Hz to 20KHz $V_{COM}=600mVp-p$ @ $R_L=32\Omega$,		-80		dB

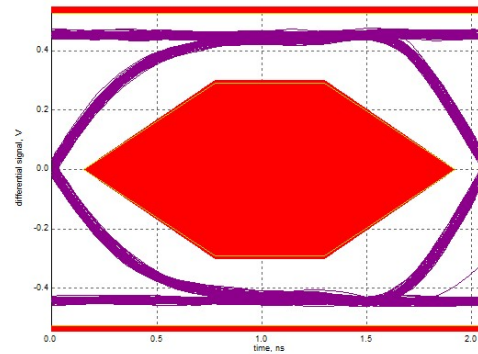
Capacitance (Ta=25°C, VCC=3.3V, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off capacitance	C_{OFF}	F=100KHz		5		pF
On capacitance	C_{ON}	F=100KHz		7		pF

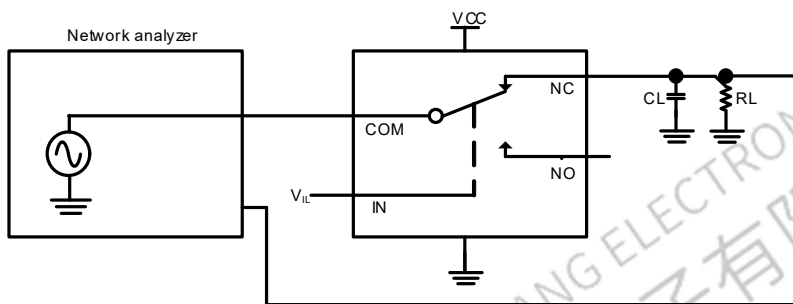
Typical Characteristics (Ta=25°C, VCC=3.3V, unless otherwise noted)



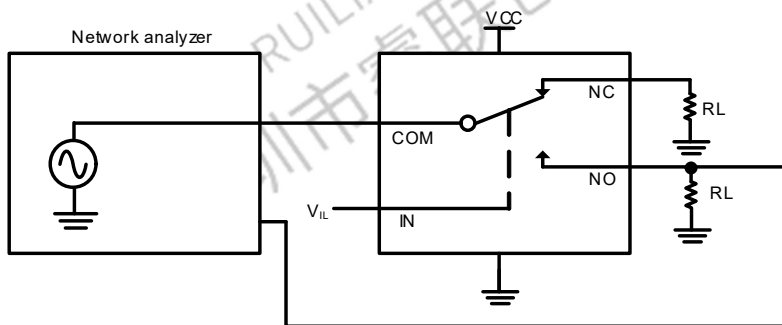
Bandwidth



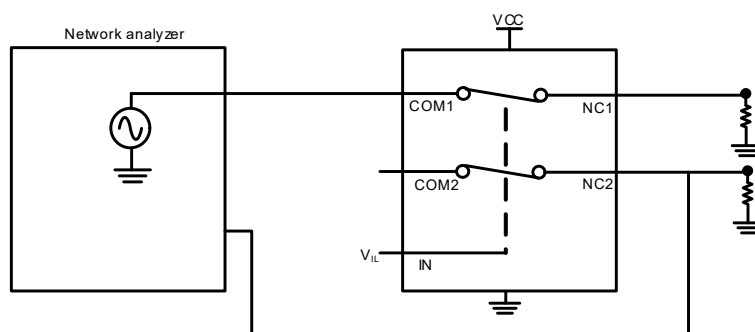
Eye Diagram (480Mbps)



Bandwidth



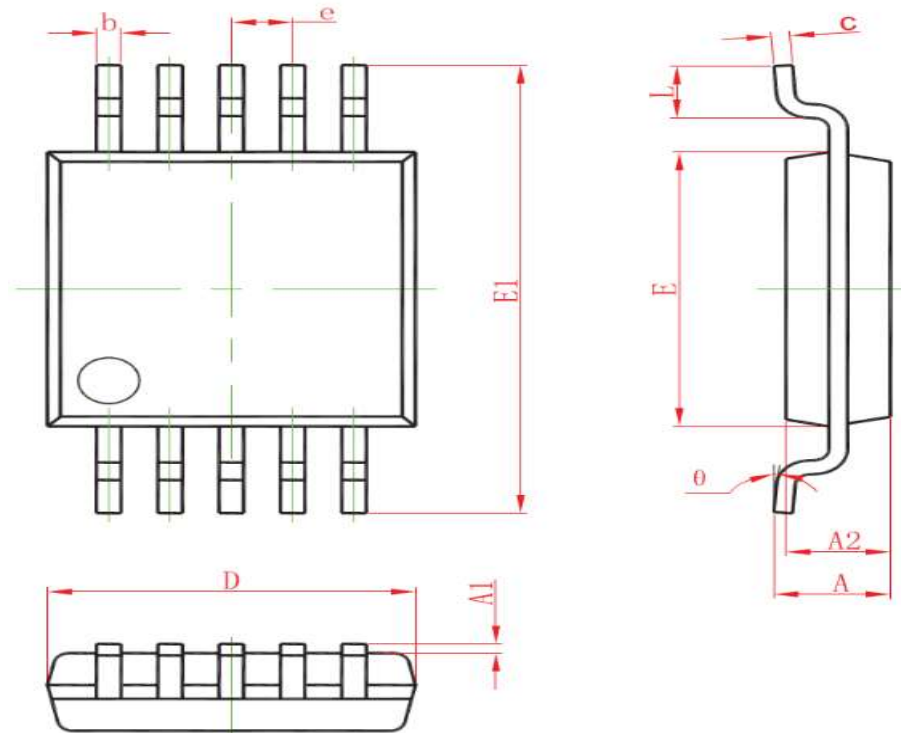
Off isolation



Crosstalk

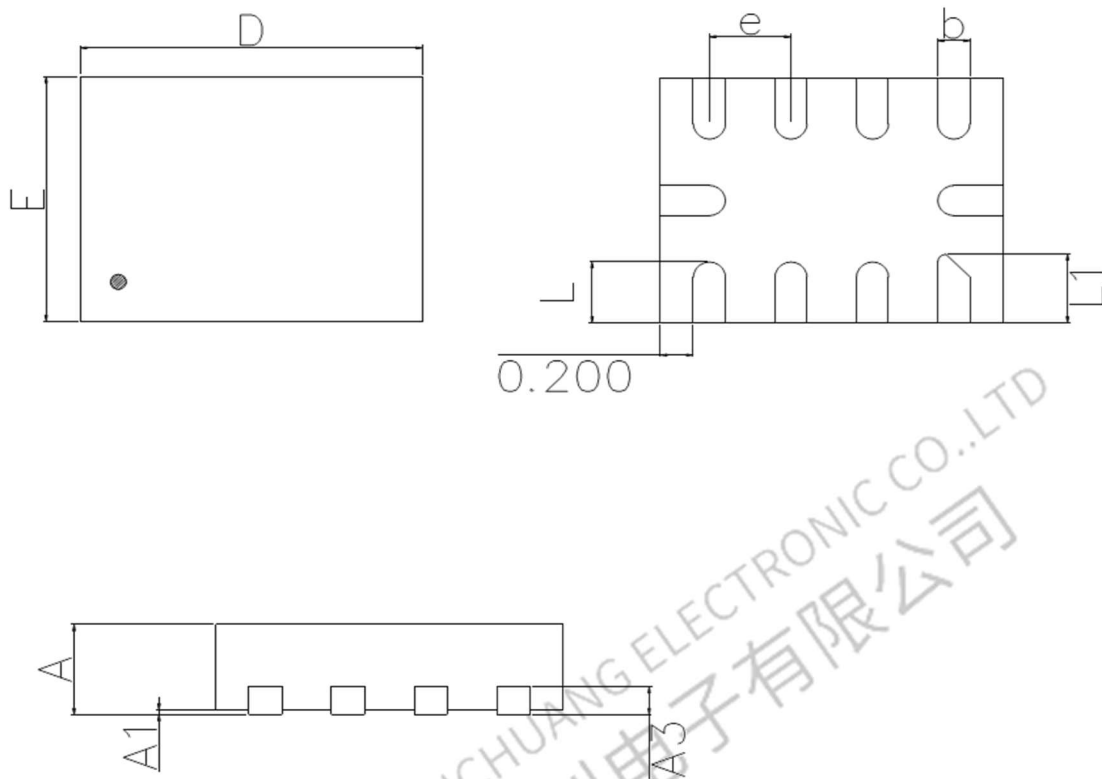
Package Outline Dimensions

MSOP-10L



Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.820	1.100
A1	0.020	0.150
A2	0.750	0.950
b	0.180	0.280
c	0.090	0.230
D	2.900	3.100
e	0.50(BSC)	
E	2.900	3.100
E1	4.750	5.050
L	0.400	0.800
θ	0°	6°

QFN 2.0 x 1.5 -10L



Symbol	Dimension in Millimeters		
	Min.	Typ.	Max.
A	0.500	0.550	0.600
A1	0.000		0.050
A3	0.150 Ref.		
D	1.950	2.000	2.050
E	1.450	1.500	1.550
b	0.150	0.200	0.250
e	0.500 (BSC)		
L	0.300	0.350	0.400
L1	0.350	0.400	0.450

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